



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSP752T	Issued	05. February 2022
MA#	MA001425984		
Package	PG-DSO-8-24	Weight*	83.26 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.188	2.63	2.63	26281	26281
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		431	
	non noble metal	iron	7439-89-6	0.717	0.86		8614	
	non noble metal	copper	7440-50-8	29.121	34.97	35.88	349749	358902
wire	noble metal	gold	7440-57-5	0.355	0.43	0.43	4267	4267
encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1168	
	plastics	epoxy resin	-	4.474	5.37		53731	
	inorganic material	silicondioxide	60676-86-0	44.057	52.91	58.40	529136	584035
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9774	9774
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7810	7810
glue	plastics	epoxy resin	-	0.130	0.16		1563	
	noble metal	silver	7440-22-4	0.613	0.74	0.90	7368	8931
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com